5. Method according to any of claims 1 to 4, wherein a heatable support (6) heats the substrate (1) to a temperature above a melting temperature of the solder.

65. Apparatus for dispensing flux-free solder onto substrate places of a substrate (1), comprising

a dispenser head (2), which is movable in two horizontal directions, and, optionally, in the vertical direction, the dispenser head (2) comprising

an ultrasonic head (4),

a stamp (5) having a working surface (11), which has a recess (12) open toward a lateral surface (13) of the stamp (5), wherein the stamp (5) is fastenable on the ultrasonic head (4),

a wire feed (6) having a nozzle (7) having a longitudinal borehole, through which the solder wire can be guided, wherein a longitudinal axis (14) of the wire feed (6), which extends through the longitudinal borehole of the nozzle (7), enters at the lateral surface (13) of the stamp (5) into the recess (12) and is incident on the substrate (1) within a part of the working surface (11) bounded by the recess (12), and

a cooling device (16), which is configured to keep the working temperature of the stamp (5) at a predetermined temperature.

76. Apparatus according to claim 65, further comprising

a further cooling device (15) for cooling the nozzle (7) of the wire feed (6).

87. Apparatus according to claim 65 or 76, further comprising

a drive (17) fastened on the dispenser head (2), which is configured to move the ultrasonic head (4) with the stamp (5) up and down in the vertical direction.

98. Apparatus according to any of claims 65 to 87, wherein the recess (12) of the stamp (5) is coated with a material which is poorly wettable by flux-free solder.

10. Apparatus according to any of claims 6 to 4, further comprising a heatable support (3) for heating the substrate (1) to a temperature above a melting temperature of the solder.